SN54HC139, SN74HC139 DUAL 2-LINE TO 4-LINE DECODERS/DEMULTIPLEXERS

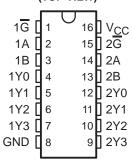
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- Targeted Specifically for High-Speed Memory Decoders and Data-Transmission Systems
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 10 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Incorporate Two Enable Inputs to Simplify Cascading and/or Data Reception

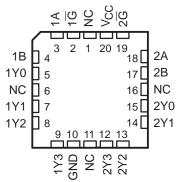
description/ordering information

The 'HC139 devices are designed high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, these decoders can minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay time of these decoders and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

SN54HC139 . . . J OR W PACKAGE SN74HC139 . . . D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



SN54HC139 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

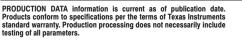
ORDERING INFORMATION

TA	PACKAGET	PACKAGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC139N	SN74HC139N
		Tube of 40	SN74HC139D	
	SOIC - D	Reel of 2500	SN74HC139DR	HC139
		Reel of 250	SN74HC139DT	
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HC139NSR	HC139
	SSOP - DB	Reel of 2000	SN74HC139DBR	HC139
		Tube of 90	SN74HC139PW	
	TSSOP - PW	Reel of 2000	SN74HC139PWR	HC139
		Reel of 250	SN74HC139PWT	
	CDIP – J	Tube of 25	SNJ54HC139J	SNJ54HC139J
-55°C to 125°C	CFP – W	Tube of 150	SNJ54HC139W	SNJ54HC139W
	LCCC - FK	Tube of 55	SNJ54HC139FK	SNJ54HC139FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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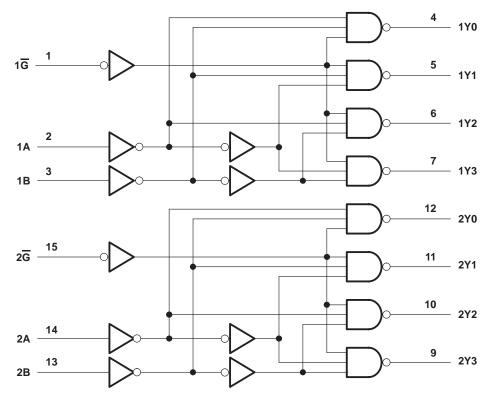
description/ordering information (continued)

The 'HC139 devices comprise two individual 2-line to 4-line decoders in a single package. The active-low enable (\overline{G}) input can be used as a data line in demultiplexing applications. These decoders/demultiplexers feature fully buffered inputs, each of which represents only one normalized load to its driving circuit.

FUNCTION TABLE

	INPUTS		OUTPUTS						
G	SEL	ECT		OUTPUTS					
G	В	Α	Y0	Y1	Y2	Y3			
Н	Х	Χ	Н	Н	Н	Н			
L	L	L	L	Н	Н	Н			
L	L	Н	Н	L	Н	Н			
L	Н	L	Н	Н	L	Н			
L	Н	Н	Н	Н	Н	L			

logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 \
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (se	ee Note 1)	±20 m/
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CO}$	c) (see Note 1)	±20 m/
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		±25 m/
Continuous current through V _{CC} or GND		±50 m/
Package thermal impedance, θ _{JA} (see Note 2):	D package	73°C/V
	DB package	82°C/V
	N package	67°C/V
	NS package	64°C/V
	PW package	108°C/V
Storage temperature range, T _{stg}		-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN	N54HC13	9	SN74HC139					
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		2	5	6	2	5	6	V	
		V _{CC} = 2 V	1.5			1.5				
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V	
		VCC = 6 V	4.2			4.2				
		V _{CC} = 2 V			0.5			0.5		
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V	
		V _{CC} = 6 V			1.8			1.8		
VI	Input voltage		0		VCC	0		VCC	V	
Vo	Output voltage		0		VCC	0		VCC	V	
		V _{CC} = 2 V			1000			1000		
Δt/Δν	Input transition rise/fall time	$V_{CC} = 4.5 V$			500			500	ns	
		V _{CC} = 6 V			400			400		
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

SN54HC139, SN74HC139 DUAL 2-LINE TO 4-LINE DECODERS/DEMULTIPLEXERS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	TEST CONDITIONS		Vaa	Т	A = 25°C	;	SN54HC139		SN74HC139		
PARAMETER			VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
		I _{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	
	VI = VIH or VIL		4.5 V		0.001	0.1		0.1		0.1	
VOL			6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
C _i			2 V to 6 V		3	10		10		10	pF

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

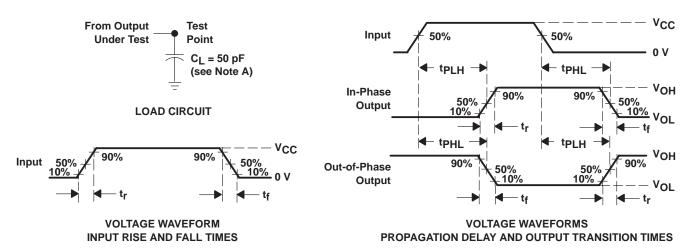
DADAMETER	FROM	TO (OUTPUT)	FROM TO		T,	4 = 25°C	;	SN54F	IC139	SN74H	IC139	
PARAMETER	(INPUT)		vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V		47	175		255		220		
	A or B	Y	Υ	4.5 V		14	35		51		44	
			6 V		12	30		44		38		
^t pd	G	Y	2 V		39	175		255		220	ns	
			4.5 V		11	35		51		44		
			6 V		10	30		44		38		
			Y	2 V		38	75		110		95	
t _t				Υ	4.5 V		8	15		22		19
			6 V		6	13		19		16		

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per decoder	No load	25	pF

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 6 \ ns$, $t_f = 6 \ ns$.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

14 LEADS SHOWN

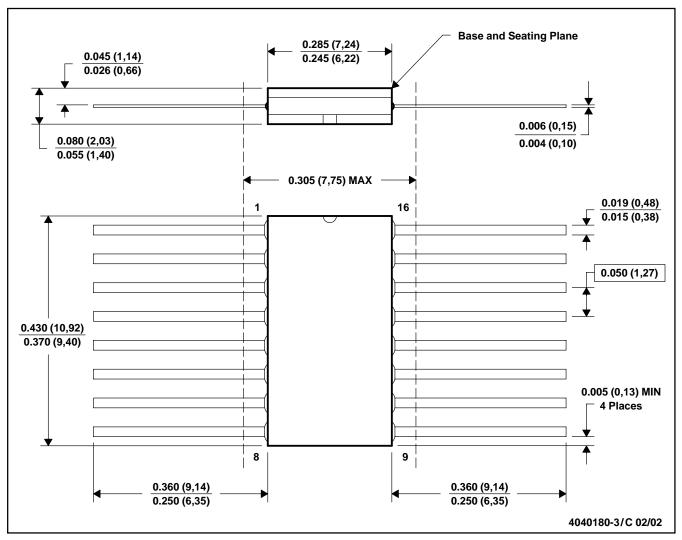


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



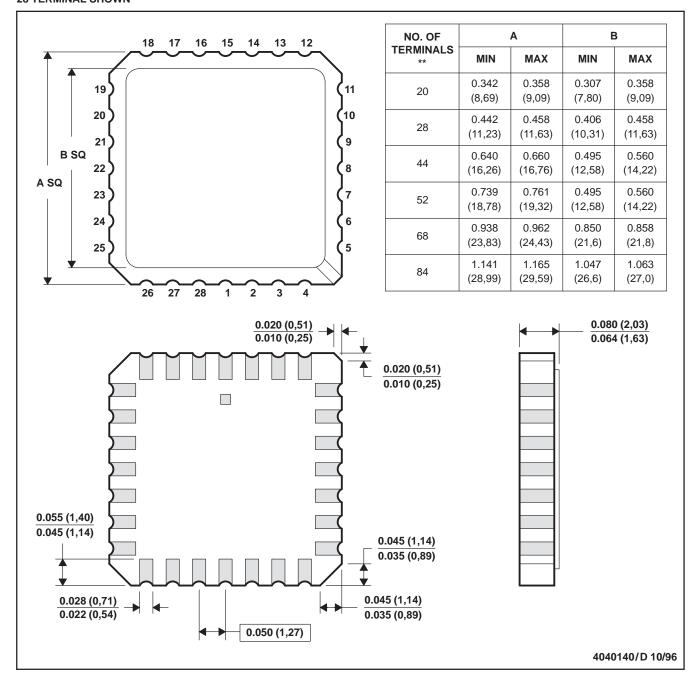
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP-1F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



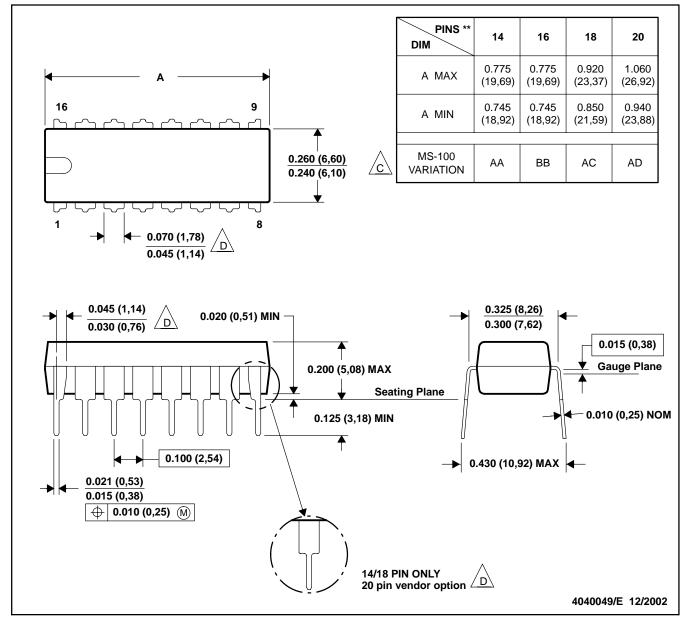
- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004



N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

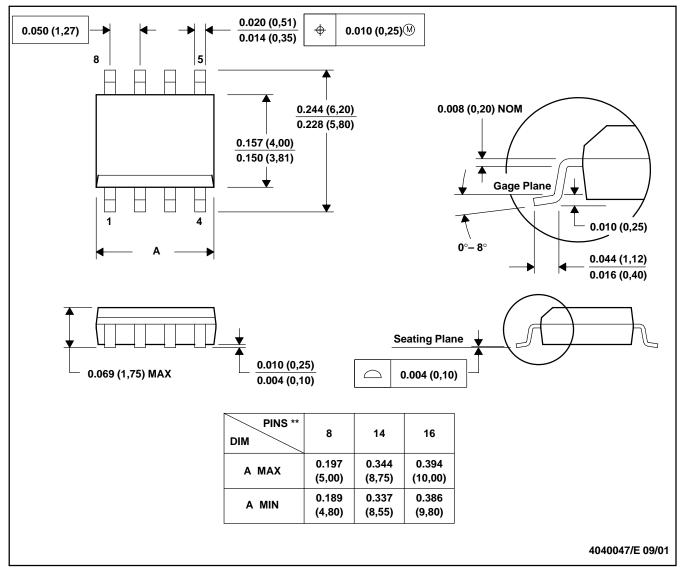
Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

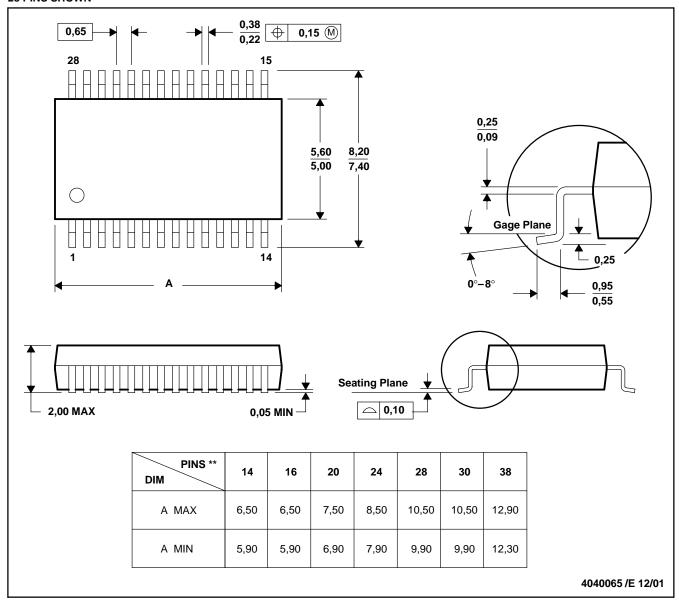
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

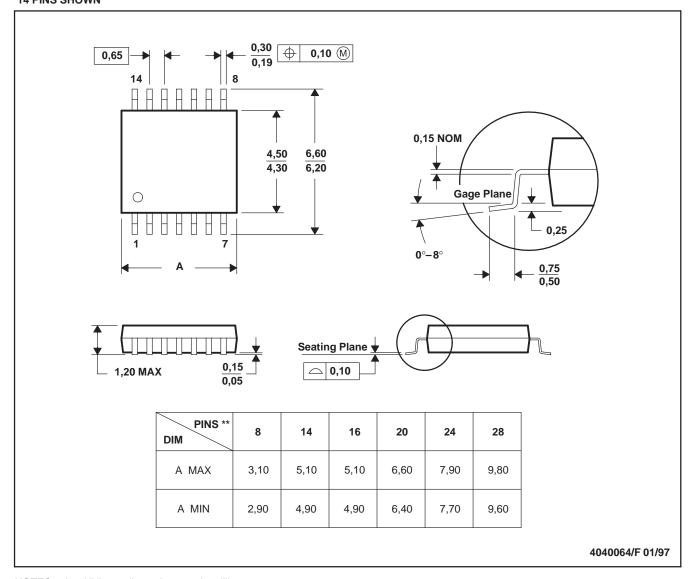
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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